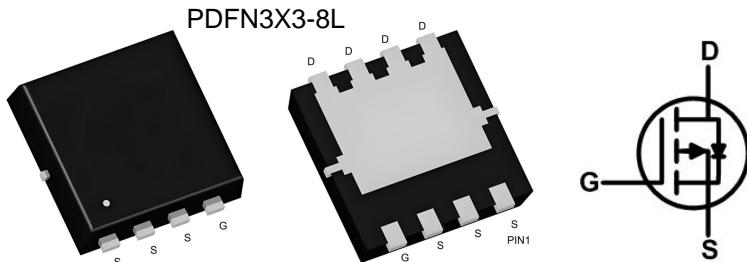


## P-Channel 30V(D-S) MOSFET

Product summary			Features	
$V_{DS}$	-30	V	<ul style="list-style-type: none"> <li>Advanced Trench technology</li> <li>Low Gate Charge</li> </ul>	
$R_{DS(ON)}$ (at $V_{GS}=-10V$ ) Typ.	16	$m\Omega$	Applications	
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ ) Typ.	26	$m\Omega$	<ul style="list-style-type: none"> <li>Load switching</li> <li>PWM Applications</li> <li>Power Management</li> </ul>	
$I_D(T_c=25^\circ C)$	-12	A		

### Pin Configuration



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAL12P03A	PDFN3X3-8L	13 "	5000pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c=25^\circ C$	-12
		$T_c=100^\circ C$	-7.6
$I_{DM}$	Pulse Drain Current Tested <sup>A</sup>	-48	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>B</sup>	25	mJ
$P_D$	Power Dissipation $T_c=25^\circ C$	4.8	W
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JC}$	Thermal Resistance-Junction to case max	26	°C/W

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

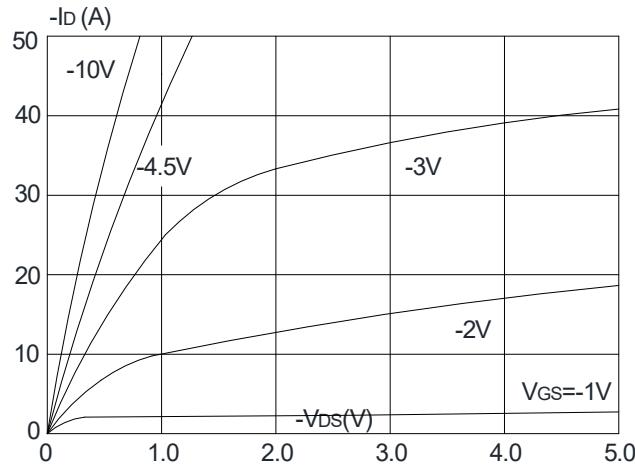
Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.5	-2.5	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance <sup>C</sup>	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-10\text{A}$	--	16	21	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5\text{A}$	--	26	36	$\text{m}\Omega$
$V_{\text{SD}}$	Diode Forward Voltage	$I_{\text{S}}=-1\text{A}, V_{\text{GS}}=0\text{V}$	--	--	-1.2	V
$I_{\text{S}}$	Continuous Source Current	$V_{\text{G}}=V_{\text{D}}=0\text{V}$ , Force Current	--	--	-12	A
Dynamic Parameters <sup>D</sup>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-15\text{V}$ $f=1\text{MHz}$	--	1610	--	pF
$C_{\text{oss}}$	Output Capacitance		--	195	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	166	--	pF
$Q_{\text{g}}$	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-9.1\text{A}$ $V_{\text{GS}}=-10\text{V}$	--	30	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	5.3	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	7.6	--	nC
$t_{\text{D(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}$ $I_{\text{D}}=-6\text{A}, V_{\text{GS}}=-10\text{V}$ $R_{\text{GEN}}=2.5\Omega$	--	14	--	ns
$t_{\text{r}}$	Turn-on Rise Time		--	20	--	ns
$t_{\text{D(off)}}$	Turn-off Delay Time		--	95	--	ns
$t_{\text{f}}$	Turn-off Fall Time		--	65	--	ns

Note:

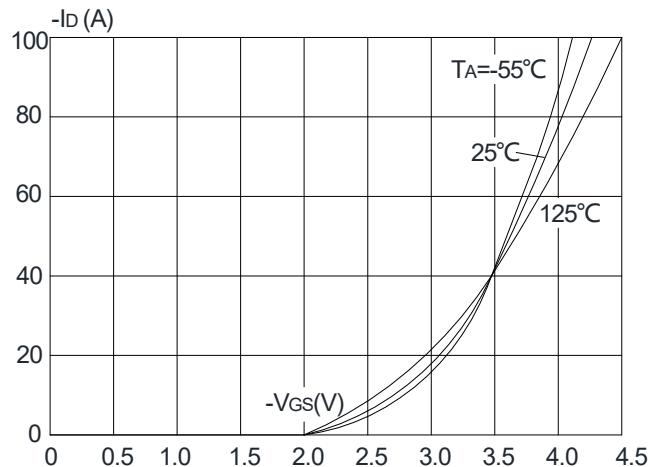
- A. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- B. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-15\text{V}, V_{\text{GS}}=-10\text{V}, L=0.5\text{mH}, I_{\text{AS}}=-10\text{A}, R_g=25\Omega, T_J=25^\circ\text{C}$ .
- C. .Pulse Test: Pulse Width $\leqslant 300\text{us}$ ,Duty cycle $\leqslant 2\%$ .
- D. Guaranteed by design, not subject to production testing.

## Typical Characteristics

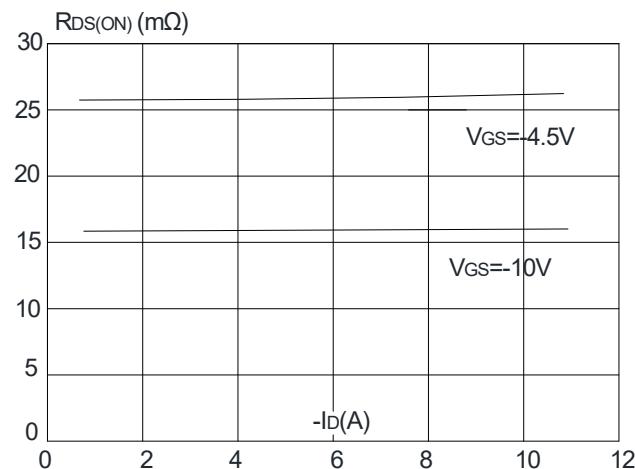
**Figure 1:** Output Characteristics



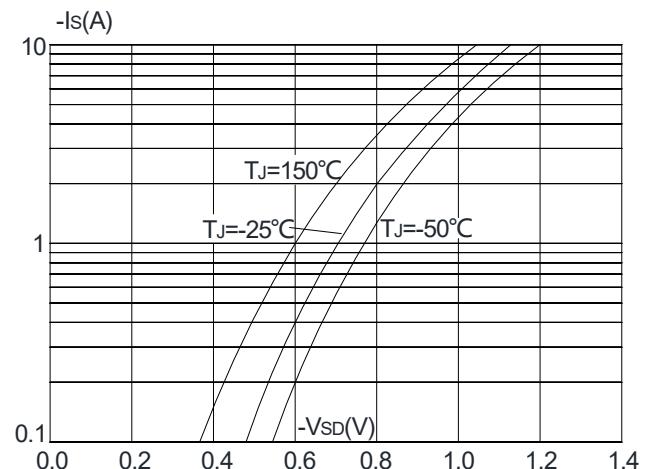
**Figure 2:** Typical Transfer Characteristics



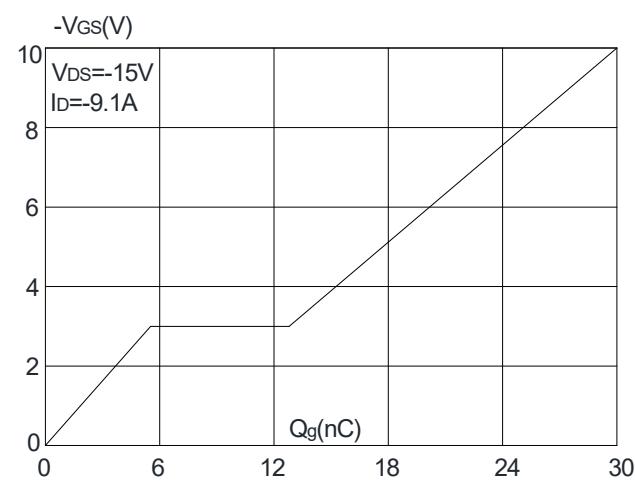
**Figure 3:** On-resistance vs. Drain Current



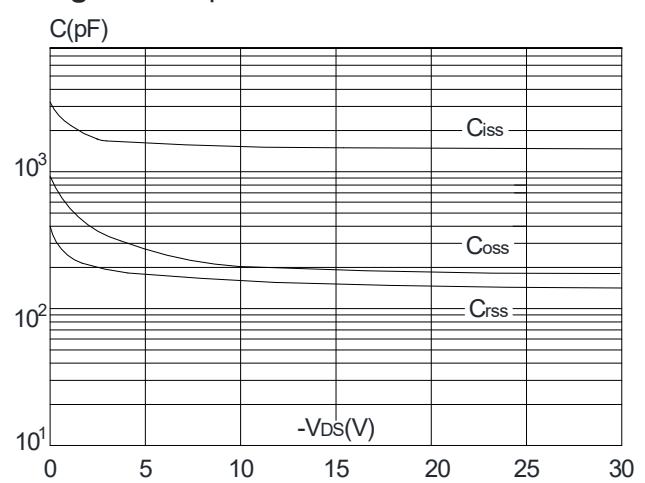
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

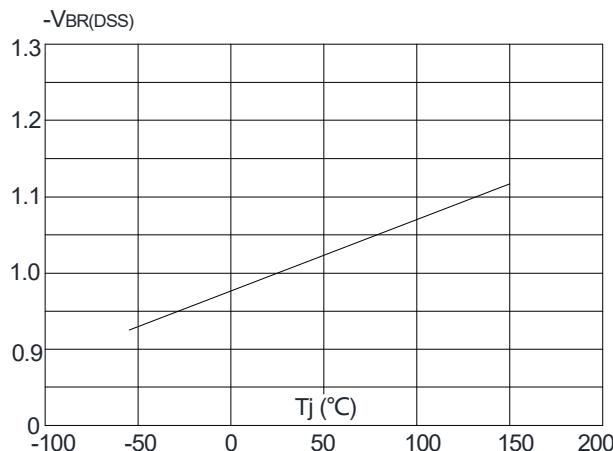


**Figure 6:** Capacitance Characteristics

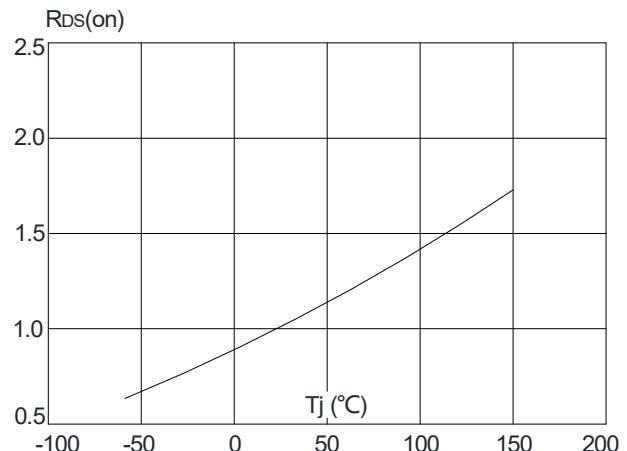


## Typical Characteristics

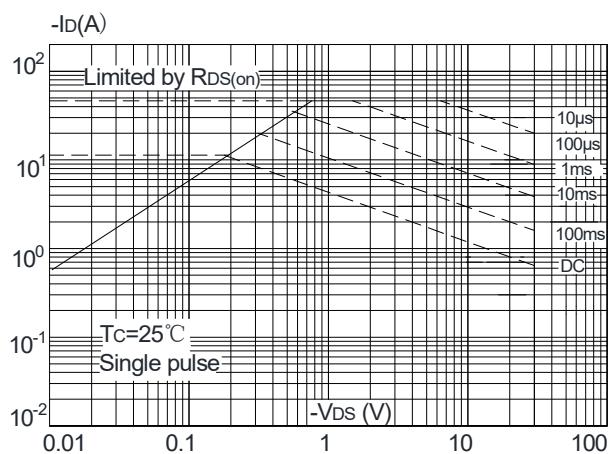
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



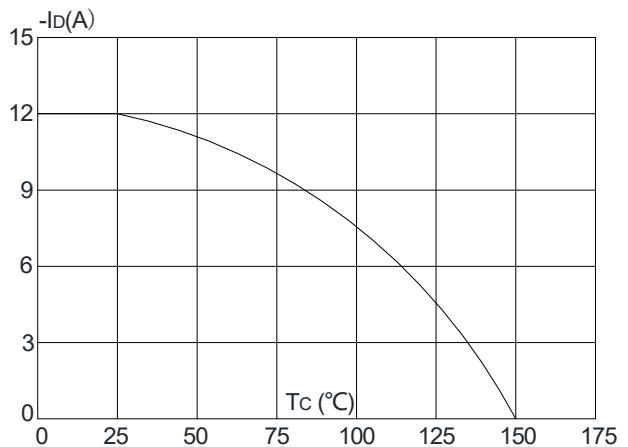
**Figure 8:** Normalized on Resistance vs. Junction Temperature



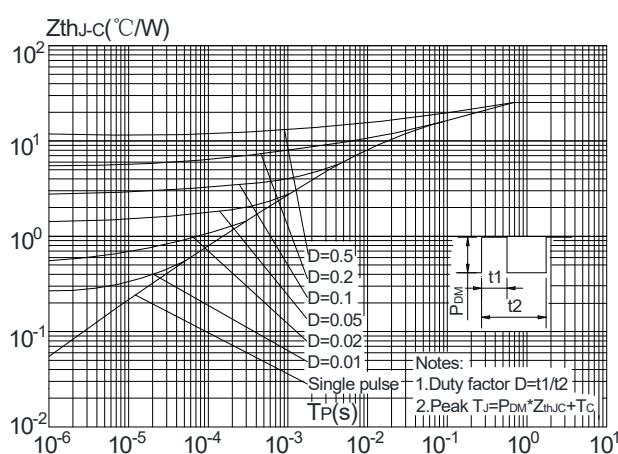
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

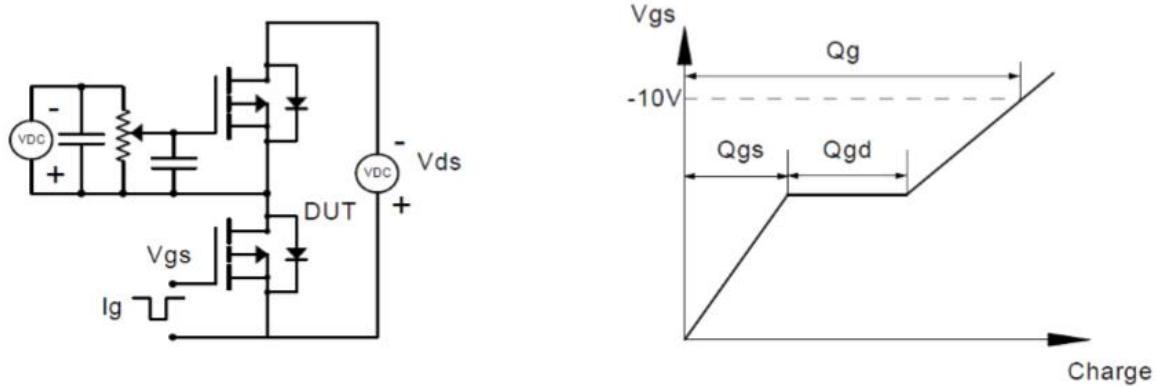


**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

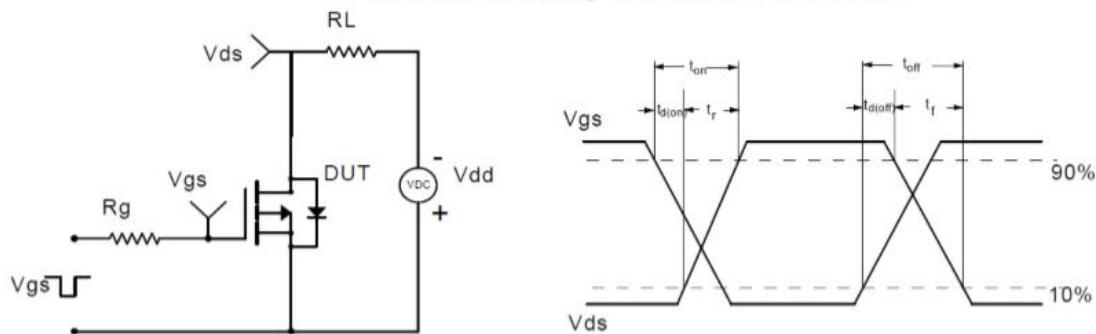


## Test Circuit

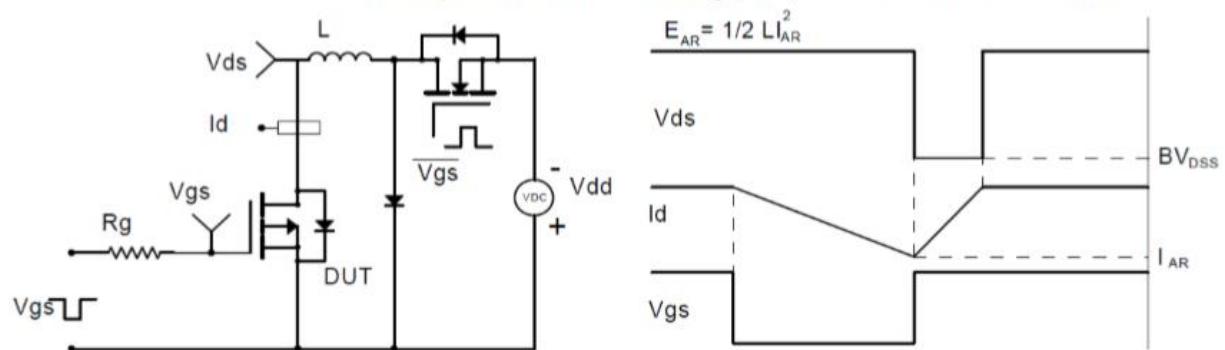
Gate Charge Test Circuit &amp; Waveform



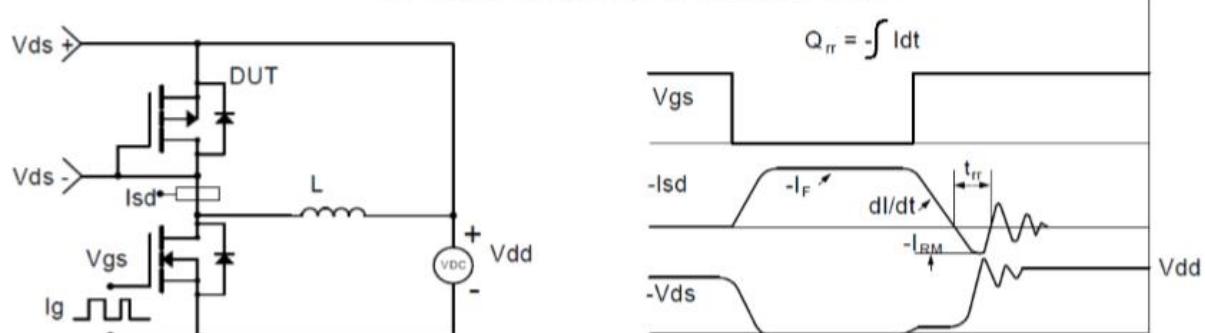
Resistive Switching Test Circuit &amp; Waveforms

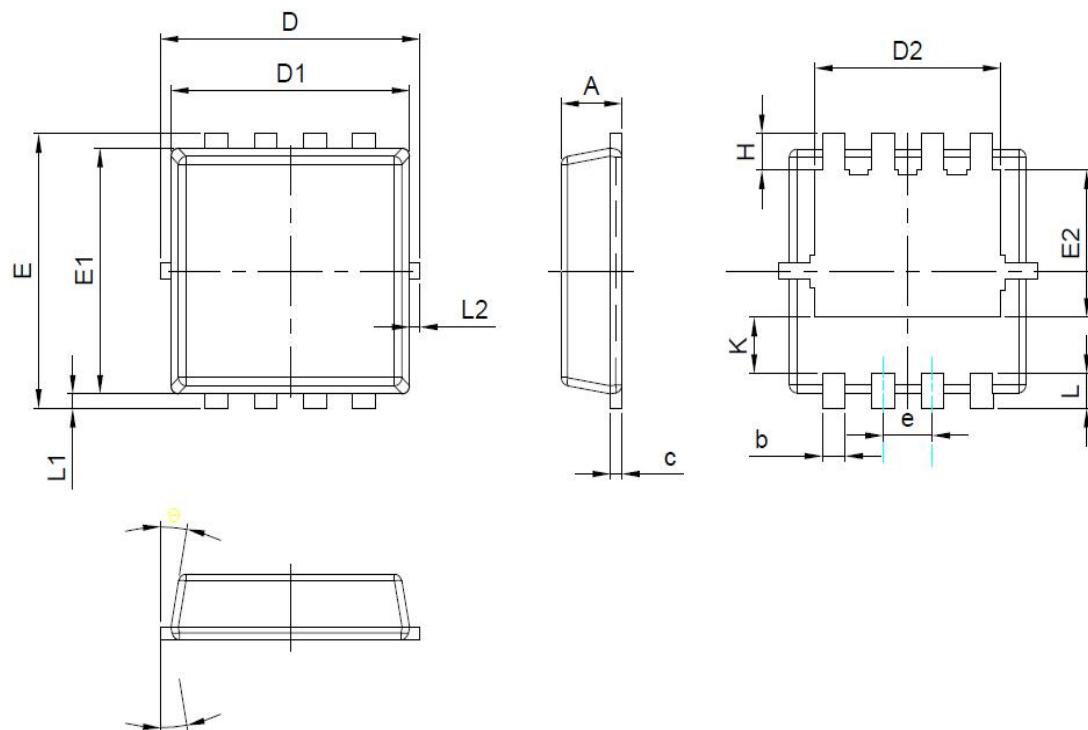


Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms



**PDFN3X3-8L Package Information**


SYMBOL	MIN	NOM	MAX
A	0.70	0.80	0.90
b	0.25	0.30	0.39
c	0.14	0.15	0.25
D	3.20	3.30	3.40
D1	3.00	3.15	3.30
D2	2.35	2.45	2.55
e	0.65 BSC		
E	3.25	3.35	3.45
E1	2.85	3.00	3.15
E2	1.635	1.735	1.835
H	0.33	0.48	0.63
K	0.585	0.685	0.785
L	0.30	0.40	0.50
L1	0.05	0.15	0.25
L2	-	-	0.15
Θ	8°	10°	12°